

PART ONE: General description

Nitride

Process name

Process Code

07/12/00

Last Update

Udo Lang

Author

Contact Information (Email)

.

General description of process

PART TWO: Details

RIE Etching

Pressure Set

185

Oxygen Set

0

RF Power Set

105

CHF3 Set

0

End Point Set

900

SF6 Set

55

Process Time

47

min

Base Pressure Set

150

PART THREE: General Comments

Etch rate – Approx. 200 (nm/min)